

FEATURES

| 260W Peak Pulse Power (tp=8/20µs)

| Bi-directional configurations

| Working voltages : 24 V

| Low leakage current

| Low clamping voltage

APPLICATIONS

| Handsets and Accessories

| Personal Digital Assestants(PDA's)

| Portable Instrumentation

| Notebooks, Desktops, and Servers

| Pagers Peripherals



SOT-323



Marking

IEC COMPATIBILITY

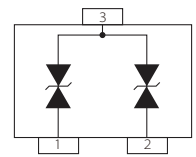
| IEC61000-4-2 (ESD) ±25kV (air), ±25kV (contact)

| IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

RoHS Compliance with 2011/65/EU

HF Compliance with IEC61249-2-21:2003



Schematic Symbol

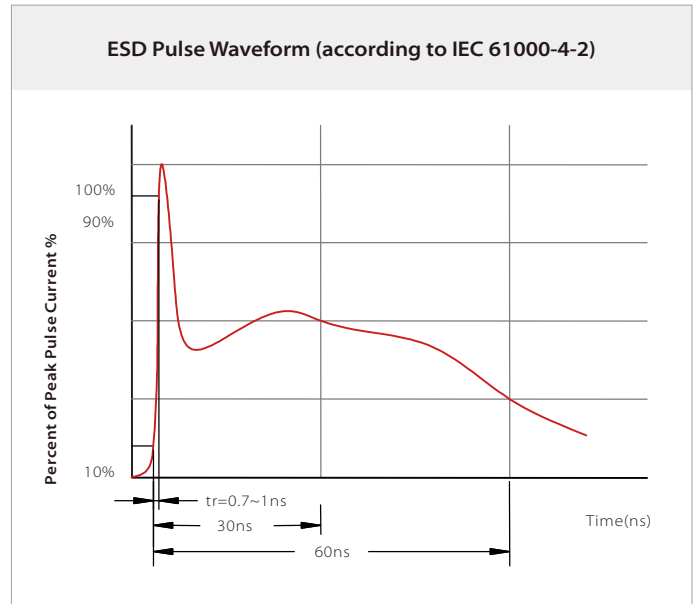
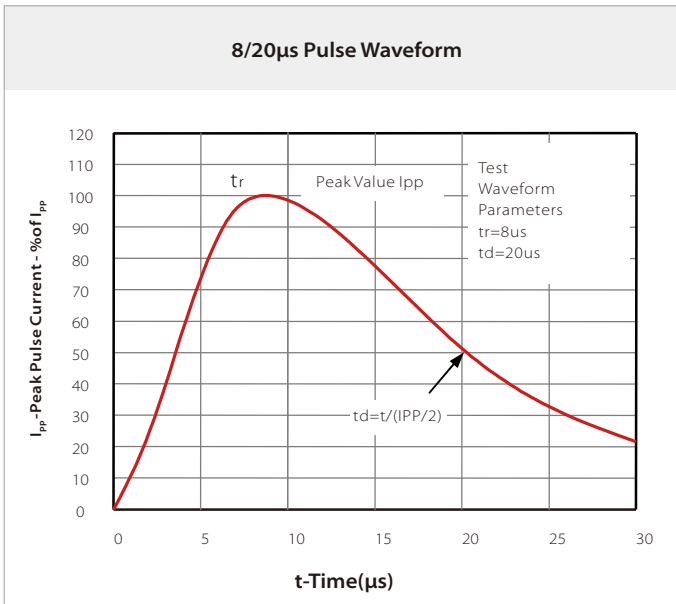
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{PP}	Peak Pulse Power (tp=8/20µs waveform)	260	Watts
T_J	Operating Temperature Range	-55 to +125	°C
T_{STG}	Storage Temperature Range	-55 to +125	°C

ELECTRICAL CHARACTERISTICS

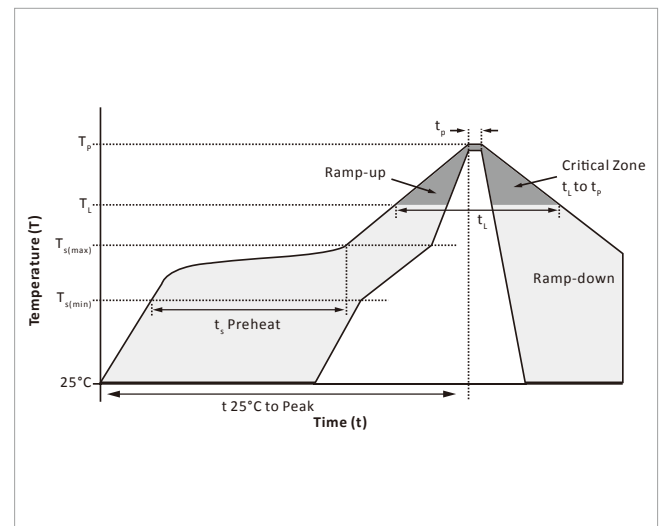
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				24	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1\text{mA}$	26.7			V
I_R	Reverse Leakage Current	$V_{RWM}=24\text{V}$		0.1	0.5	µA
V_C	Clamping Voltage (Tp=8/20us)	$I_{pp}=6\text{A}, tp=8/20\text{us}$		40	44	V
I_{PP}	Peak Pulse Current (Tp=8/20us)	tp=8/20us			6	A
C_J	Off State Junction Capacitance	$V_R=0\text{V}, f=1\text{MHz}$		14		pF

CHARACTERISTIC CURVES

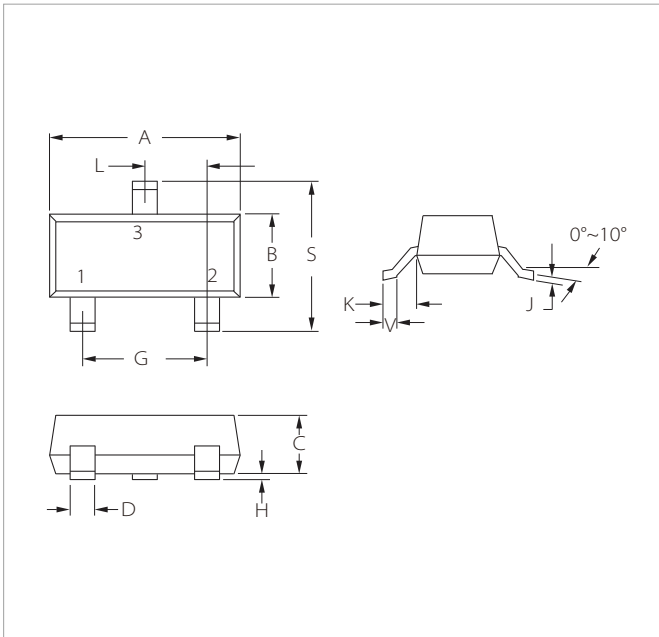


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

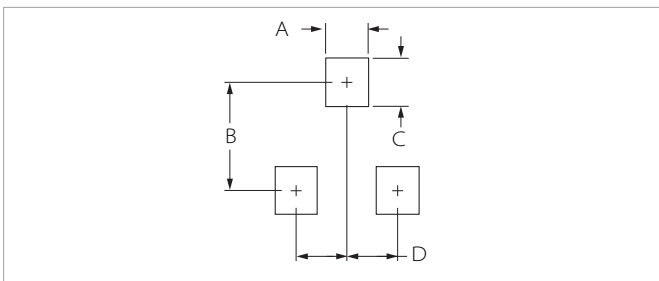


SOT-323 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.00	2.20	0.079	0.087
B	1.15	1.35	0.045	0.053
C	0.90	1.00	0.035	0.039
D	0.20	0.40	0.008	0.016
G	1.20	1.40	0.047	0.055
H	0.00	0.10	0.000	0.004
J	0.08	0.15	0.003	0.006
K	0.525REF		0.021 REF	
L	0.650TYP		0.026TYP	
S	2.15	2.45	0.085	0.096
V	0.26	0.46	0.010	0.018

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
	NOR	NOR
A	0.50	0.020
B	2.20	0.087
C	0.80	0.031
D	1.30	0.051

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE33T25B24B	SOT-323	3000PCS	7"

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